



Material Content Data Sheet



Sales Product Name		BTS3205G		Issued		27. September 2017		
MA#		MA001053006						
Package		PG-DSO-8-24		Weight*		82.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.717	0.87	0.87	8657	8657
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.717	0.87		8660	
wire	non noble metal	copper	7440-50-8	29.121	35.16	36.08	351640	360841
	noble metal	gold	7440-57-5	0.236	0.28	0.28	2847	2847
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1211
encapsulation	plastics	epoxy resin	-	4.612	5.57		55696	
	inorganic material	silicondioxide	60676-86-0	45.422	54.85	60.54	548481	605388
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9827	9827
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7852	7852
glue	plastics	epoxy resin	-	0.066	0.08		803	
	noble metal	silver	7440-22-4	0.313	0.38	0.46	3785	4588
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com